

PAT-NO: JP402027615A  
DOCUMENT-IDENTIFIER: JP 02027615 A  
TITLE: INPUT AND OUTPUT CABLE FOR EXTREMELY LOW  
TEMPERATURE  
INTEGRATED CIRCUIT  
PUBN-DATE: January 30, 1990

INVENTOR-INFORMATION:  
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APPL-NO: JP63178451  
APPL-DATE: July 18, 1988

INT-CL (IPC): H01B012/06, H01L039/06  
US-CL-CURRENT: 174/15.4

ABSTRACT:

PURPOSE: To prevent any trouble on contacts associated with heat contraction under an extremely low temperature by utilizing a vertically orientated polymer insulating layer as an insulating layer, and absorbing a heat strain due to a difference in a linear expansion among foreign materials of a signal wire, the insulating layer and a grounding conductor.

CONSTITUTION: The first vertically orientated polymer insulating layer 5 comprising a signal wire (copper) 2, the first grounding conductor (copper) 3, the second grounding conductor (copper) 4 and poly-oxymethylene, and the second

vertically orientated polymer insulating layer 6 comprising poly-oxymethylene are prepared. Then, an insulated conductor is formed by lamination by epoxy glue 7 so that the vertically orientated polymer insulating layers 5 and 6 may touch the signal wire 2. In the vertically orientated polymer insulating layers 5 and 6 a polymer crystalline granule block of which a molecule axis is orientated perpendicular to a surface of the grounding conductor intervenes between a surface that correlative signal wires are lined in parallel and the grounding conductor. Due to a spacing existing in a boundary of a crystalline granule within a surface paralleled to the grounding conductor, the heat strain may be absorbed. Accordingly any trouble on contacts associated with the heat contraction under the extremely low temperature may be prevented.

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PAT-NO: JP362091533A  
DOCUMENT-IDENTIFIER: JP 62091533 A  
TITLE: METHOD OF BONDING POLYOXYMETHYLENE  
PUBN-DATE: April 27, 1987

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APPL-NO: JP60229846  
APPL-DATE: October 17, 1985

INT-CL (IPC): C08J005/12, B29C065/52  
US-CL-CURRENT: 156/272.2

ABSTRACT:

PURPOSE: To bond polyoxymethylene firmly to each other or to other material, by irradiating its surface with electron beams and bonding it with an adhesive.

CONSTITUTION: In bonding polyoxymethylene to each other or to other material, its surface is previously irradiated with electron beams and then bonded by using an adhesive. When irradiating with electron beams, the tensile strength is affected by the dose. Particularly, when polyoxymethylene is irradiated at a dose exceeding 5Mrad, the tensile strength is extremely lowered. Hence, it is desirable that the dose is 1Mrad or below. Polyoxymethylene which has been irradiated with electron beams can be bonded

with a conventional cyanoacrylate adhesive or an epoxy adhesive.

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